

The XC6603 series is a low voltage input (0.5V) operation and provides high accuracy $\pm 15\text{mV}$ / $\pm 20\text{mV}$ and can supply large current efficiently due to its ultra low on-resistance even at low output voltages.

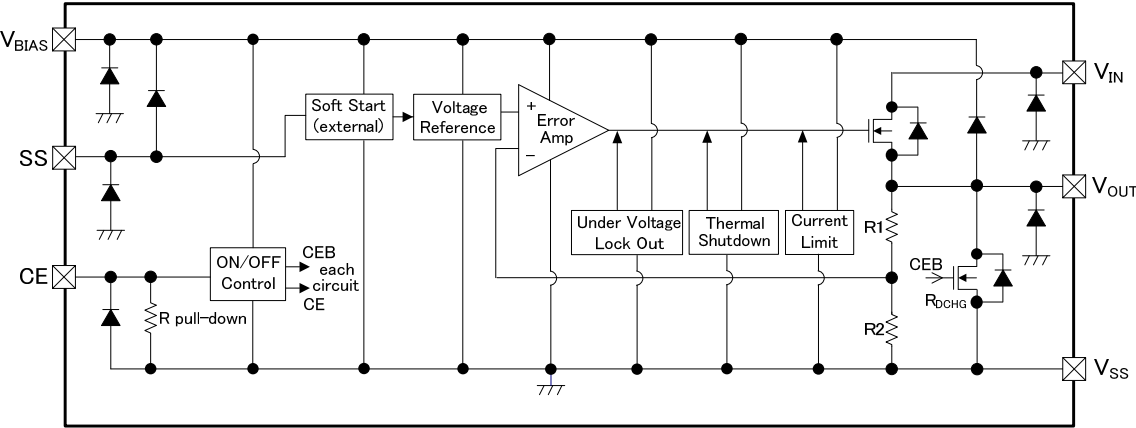
The series is ideally suited to the applications which require high current in low input/output voltages and consists of a N-channel driver transistor, a voltage reference, an error amplifier, a current limiter, a foldback circuit, a thermal shutdown (TSD) circuit, an under voltage lock out (UVLO) circuit, a soft-start circuit and a phase compensation circuit.

Output voltage is selectable in 0.1V increments within a range of 0.5V to 1.8V using laser trimming technology and ceramic capacitors can be used for the output stabilization capacitor (C_L). The inrush current (I_{RUSH}) from V_{IN} to V_{OUT} for charging C_L at start-up can be reduced and makes the V_{IN} stable. Soft-start time can be adjustable with connecting a capacitor to the SS pin. The inrush current conflicts with the soft-start time, therefore if soft-start is set longer, the inrush current is decreased.

The CE function enables the output to be turned off and the series to be put in stand-by mode resulting in greatly reduced power consumption. At the time of entering the stand-by mode, the series enables the electric charge at the output capacitor (C_L) to be discharged via the internal switch. As a result the V_{OUT} pin quickly returns to the V_{SS} level.

BLOCK DIAGRAMS

Type A



PRODUCT CLASSIFICATION

Ordering Information

XC6603①②③④⑤⑥⑦

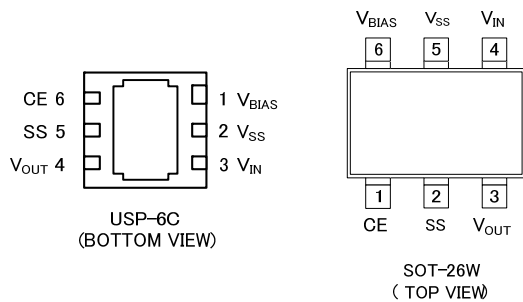
DESIGNATOR	ITEM	SYMBOL	DESCRIPTION
①	Type	A	Refer to Selection Guide
②③	Output Voltage	05~18	e.g. 1.2V → ②=1, ③=2
④	Output Voltage Accuracy	1	±0.015V (V _{OUT} <1.2V), ±0.020V (V _{OUT} ≥1.2V)
⑤⑥⑦ (*1)	Packages (Order Unit)	ER-G	USP-6C (3,000/Reel)
		MR-G	SOT-26W (3,000/Reel)

(*1) The “-G” suffix denotes Halogen and Antimony free as well as being fully RoHS compliant.

Selection Guide

TYPE	SOFT-START	CURRENT LIMITER	THERMAL SHUTDOWN	UVLO	CE PULL-DOWN RESISTOR	C _L AUTO DISCHARGE
A	Adjustable	Yes	Yes	Yes	Yes	Yes

PIN CONFIGURATION



*The dissipation pad for the USP-6C package should be solder-plated in recommended mount pattern and metal masking so as to enhance mounting strength and heat release. If the pad needs to be connected to other pins, it should be connected to the V_{SS} (No. 2) pin.

PIN ASSIGNMENT

PIN NUMBER		PIN NAME	FUNCTIONS
USP-6C	SOT-26W		
1	6	V _{BIAS}	Power Supply Input
3	4	V _{IN}	Driver Transistor Input
4	3	V _{OUT}	Output
5	2	SS	Soft-Start Capacitor Connection
2	5	V _{SS}	Ground
6	1	CE	ON/OFF Control

FUNCTION CHART

PIN NAME	SIGNAL	STATUS
CE	L	Stand-by
	H	Active
	OPEN	Stand-by

■ ABSOLUTE MAXIMUM RATINGS

Ta=25

PARAMETER		SYMBOL	RATINGS	UNITS
Bias Voltage		V _{BIAS}	-0.3~+6.5	V
Input Voltage		V _{IN}	-0.3~+6.5	V
Output Current		I _{OUT}	1.65 ^(*1)	A
Output Voltage ^(*2)		V _{OUT}	-0.3~V _{BIAS} +0.3 or +6.5	V
			-0.3~V _{IN} +0.3 or +6.5	
CE Input Voltage		V _{CE}	-0.3~+6.5	V
SS Pin Voltage ^(*3)		SS	-0.3~V _{BIAS} +0.3 or +6.5	V
Power Dissipation	USP-6C	Pd	120	mW
			1000 (PCB mounted) ^(*4)	
	SOT-26W		250	
			600 (PCB mounted) ^(*4)	
Operating Ambient Temperature		Topr	-40~+85	°C
Storage Temperature		Tstg	-55~+125	°C

* All voltages are described based on the V_{SS} pin.

(*1) $I_{OUT} \leq Pd / (V_{IN} - V_{OUT})$

(*2) The maximum value should be either V_{BIAS}+0.3, V_{IN}+0.3 or +6.5 in the lowest.

(*3) The maximum value should be either V_{BIAS}+0.3 or +6.5 in the lowest.

(*4) The power dissipation measured with the test board condition is listed as reference data.

Please refer to page 25 ~ 26 for details.

ELECTRICAL CHARACTERISTICS

Ta=25

PARAMETER	SYMBOL	CONDITIONS		MIN.	TYP.	MAX.	UNITS	CIRCUIT
Bias Voltage	V _{BIAS}			2.5	-	6.0	V	①
Input Voltage	V _{IN}			0.5	-	3.0	V	①
Output Voltage	V _{OUT(E)} ^(*1)	I _{OUT} =100mA	V _{OUT(T)} < 1.2V	-0.015	V _{OUT(T)} ^(*2)	+0.015	V	①
			V _{OUT(T)} ≥ 1.2V	-0.020		+0.020		
Maximum Output Current ^(*3)	I _{OUTMAX}	V _{OUT(T)} < 1.2V, V _{BIAS} =V _{CE} =2.5V		1.0	-	-	A	①
		V _{OUT(T)} ≥ 1.2V, V _{BIAS} =V _{CE} =V _{OUT(T)} +1.3V						
Load Regulation	ΔV _{OUT}	1mA ≤ I _{OUT} ≤ 1A		-	37	68	mV	①
Dropout Voltage	V _{dif} ^(*4)	I _{OUT} =1A		-	E-1 ^(*5)		mV	①
Supply Current 1 ^(*6)	I _{BIAS}	I _{OUT} =0A		76	100	143	μA	②
Supply Current 2	I _{IN}	I _{OUT} =0A	V _{OUT(T)} < 1.2V	0.1	-	8.7	μA	②
			V _{OUT(T)} ≥ 1.2V	3.9	-	14.2		
Stand-by Current 1	I _{BIAS_STB}	V _{BIAS} =6.0V, V _{IN} =3.0V, V _{CE} =V _{SS}		-	0.01	0.10	μA	②
Stand-by Current 2	I _{IN_STB}	V _{BIAS} =6.0V, V _{IN} =3.0V, V _{CE} =V _{SS}		-	0.01	0.15	μA	②
Bias Line Regulation	ΔV _{OUT} / (ΔV _{BIAS} •V _{OUT})	V _{OUT(T)} < 1.2V, V _{CE} =V _{BIAS} , 2.5V ≤ V _{BIAS} ≤ 6.0V		-	0.01	0.10	%V	①
		V _{OUT(T)} ≥ 1.2V, V _{CE} =V _{BIAS} , V _{OUT(T)} +1.3V ≤ V _{BIAS} ≤ 6.0V						
Input Line Regulation	ΔV _{OUT} / (ΔV _{IN} •V _{OUT})	V _{OUT(T)} +0.1V ≤ V _{IN} ≤ 3.0V		-	0.01	0.10	%V	①
Bias UVLO Voltage	V _{BIAS_UVL0D}			V _{SS}	-	1.28	V	①
Bias UVLO Release Voltage	V _{BIAS_UVL0R}			2.5	-	6.0	V	①
Input UVLO Voltage	V _{IN_UVL0D}			V _{SS}	-	0.23	V	①
Input UVLO Release Voltage	V _{IN_UVL0R}			0.5	-	3.0	V	①
Output Voltage Temperature Characteristics	ΔV _{OUT} / (ΔT _{opr} •V _{OUT})	I _{OUT} =100mA -40℃ ≤ T _{opr} ≤ 85℃		-	±30	-	ppm/℃	①
Bias Ripple Rejection Ratio	V _{BIAS_PSRR}	V _{BIAS} =V _{CE} =3.6V _{DC} +0.2V _{p-pAC} I _{OUT} =100mA, f=1kHz, C _{BIAS} =OPEN		-	60	-	dB	③
Input Ripple Rejection Ratio	V _{IN_PSRR}	V _{IN} =V _{OUT(T)} +0.3V _{DC} +0.2V _{p-pAC} I _{OUT} =100mA, f=1kHz, C _{IN} =OPEN		-	75	-	dB	③
Current Limit ^(*3)	I _{LIM}	V _{OUT} ={V _{OUT} @I _{OUT} =1A}×0.95		1.0	1.3	-	A	①
Short - Circuit Current	I _{SHORT}	V _{OUT} =V _{SS}		-	90	-	mA	①
Thermal Shutdown Detect Temperature	T _{TSD}	Junction Temperature		-	150	-	℃	①
Thermal Shutdown Release Temperature	T _{TSR}	Junction Temperature		-	125	-	℃	①
Thermal Shutdown Hysteresis Width	T _{TSD} -T _{TSR}	Junction Temperature		-	25	-	℃	①
C _L Auto-Discharge Resistance	R _{DCHG}	V _{CE} =V _{SS} , V _{OUT} =V _{OUT(T)}		130	190	255	Ω	①
CE "H" Level Voltage	V _{CEH}			0.65	-	6.00	V	④
CE "L" Level Voltage	V _{CEL}			V _{SS}	-	0.41	V	④
CE "H" Level Current	I _{CEH}	V _{BIAS} =V _{CE} =6.0V		3.2	6.0	10.6	μA	④
CE "L" Level Current	I _{CEL}	V _{BIAS} =6.0V, V _{CE} =V _{SS}		-0.1	-	0.1	μA	④
SS Pin Current	I _{soft}	SS Pin=V _{SS}		3.60	5.00	6.55	μA	⑤
Soft-Start Threshold Voltage ^(*7)	V _{soft}			(0.927)	(1.085)	(1.243)	V	-

NOTE:

Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V, V_{IN}=V_{OUT(T)}+0.3V, I_{OUT}=1mA, C_{BIAS}=C_{IN}=1.0\mu F, C_L=2.2\mu F, SS\ Pin=OPEN$

(*)1 $V_{OUT(E)}$ = Effective output voltage

(*)2 $V_{OUT(T)}$ = Nominal output voltage

(*)3 Mount conditions affect heat dissipation. Maximum output current is not guaranteed when TSD starts to operate earlier.

(*)4 $V_{dif}=\{V_{IN1}-V_{OUT1}\}$

V_{IN1} is an input voltage when V_{OUT1} appears at the output during decreasing input voltage gradually.

V_{OUT1} is a voltage equal to 98% of the output voltage where $V_{BIAS}=V_{CE}=3.6$ and $V_{IN}=V_{OUT(T)}+0.3V$ at $I_{OUT}=1A$ is input to the V_{IN} pin.

(*)5 Please refer to the table E-1 named DROPOUT VOLTAGE CHART

(*)6 Supply current 1 (I_{BIAS}) may be fluctuated because that some bias current flows into the output.

(*)7 Design value

ELECTRICAL CHARACTERISTICS (Continued)

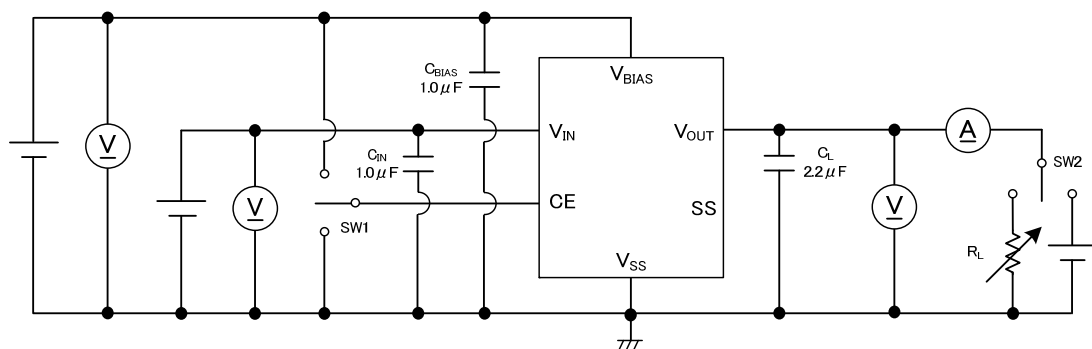
Dropout Voltage Chart

NOMINAL OUTPUT VOLTAGE	E-1														
	DROPOUT VOLTAGE (mV)														
	V _{BIAS} =3.0V			V _{BIAS} =3.3V			V _{BIAS} =3.6V			V _{BIAS} =4.2V			V _{BIAS} =5.0V		
	V _{GS} (V)	V _{dif} (mV)		V _{GS} (V)	V _{dif} (mV)		V _{GS} (V)	V _{dif} (mV)		V _{GS} (V)	V _{dif} (mV)		V _{GS} (V)	V _{dif} (mV)	
		TYP.	MAX.		TYP.	MAX.		TYP.	MAX.		TYP.	MAX.		TYP.	MAX.
V _{OUT(T)}															
0.5	2.5	152	218	2.8	146	213	3.1	146	213	3.7	140	208	4.5	137	206
0.6	2.4	155	223	2.7			3.0			3.6			4.4		
0.7	2.3			2.6			2.9			3.5			4.3		
0.8	2.2	158	228	2.5	152	218	2.8			3.4			4.2		
0.9	2.1	162	233	2.4	155	223	2.7			3.3			4.1		
1.0	2.0	165	238	2.3			2.6			3.2	146	213	4.0	140	208
1.1	1.9	167	243	2.2	158	228	2.5	152	218	3.1			3.9		
1.2	1.8	169	253	2.1	162	233	2.4	155	223	3.0			3.8		
1.3	1.7	179	268	2.0	165	238	2.3			2.9			3.7		
1.4	1.6	189	283	1.9	167	243	2.2	158	228	2.8			3.6		
1.5	1.5	202	303	1.8	169	253	2.1	162	233	2.7			3.5		
1.6	1.4	213	328	1.7	179	268	2.0	165	238	2.6			3.4		
1.7	1.3	225	373	1.6	189	283	1.9	167	243	2.5	152	218	3.3		
1.8	1.2	255	423	1.5	202	303	1.8	169	253	2.4	155	223	3.2	146	213

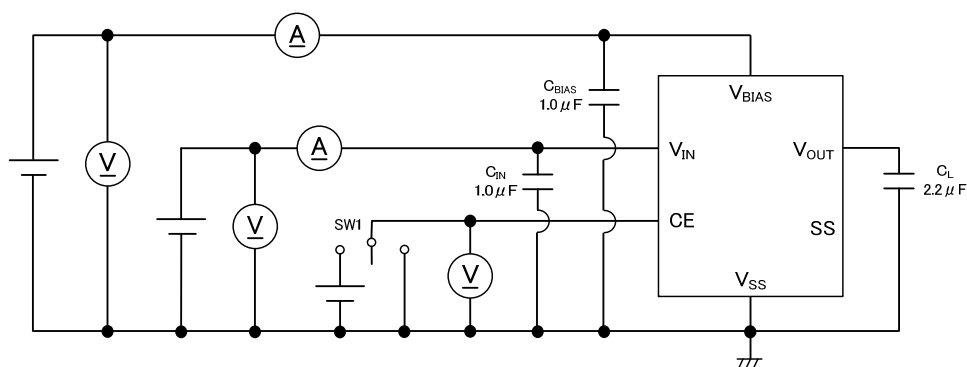
* Dropout voltage is defined as the V_{GS}(=V_{BIAS}-V_{OUT(E)}) of the driver transistor.

■ TEST CIRCUITS

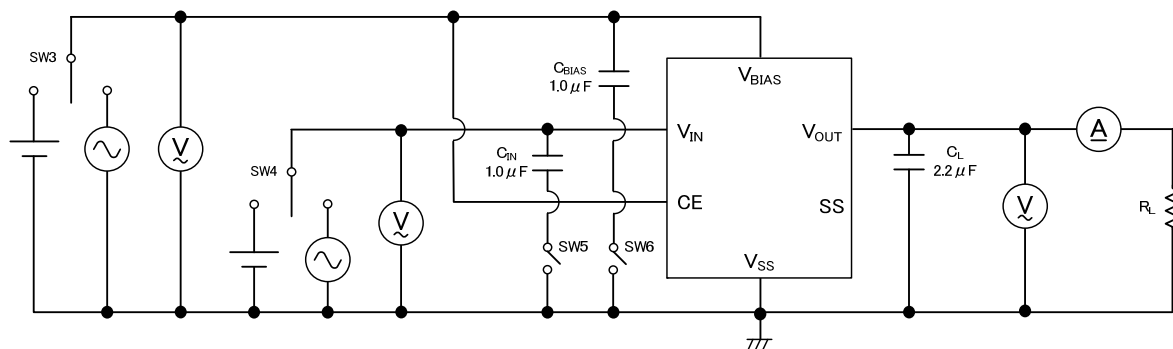
CIRCUIT



CIRCUIT②

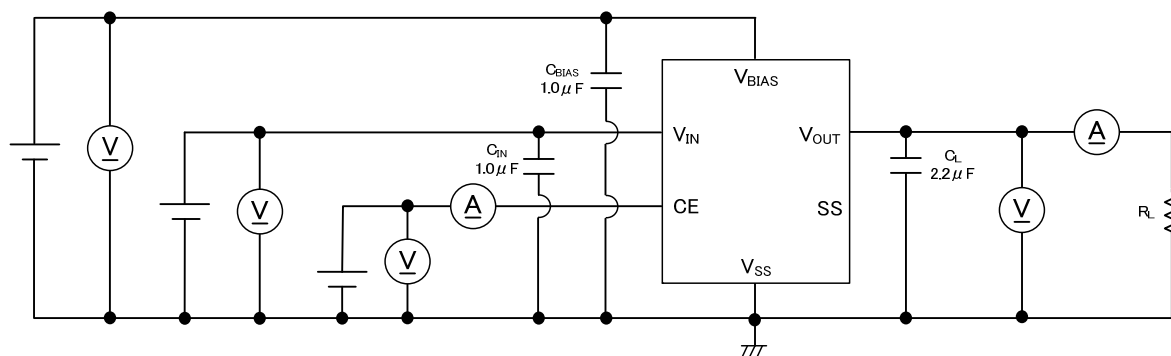


CIRCUIT③

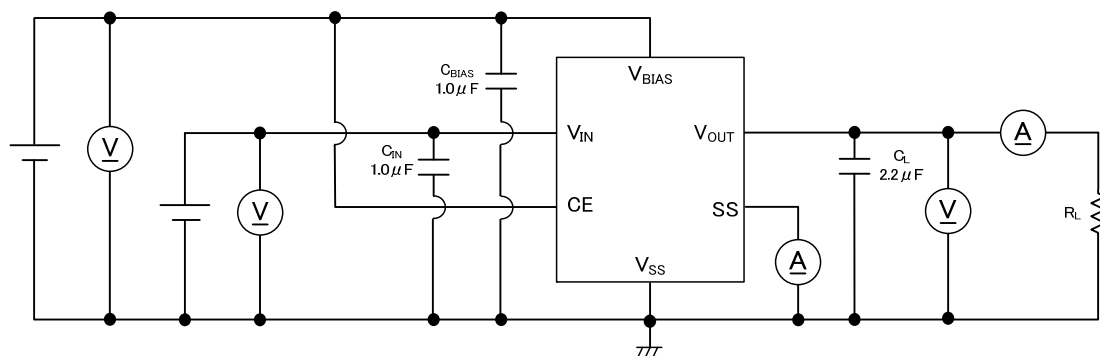


TEST CIRCUITS (Continued)

CIRCUIT④



CIRCUIT⑤



■ OPERATIONAL DESCRIPTION

The voltage divided by resistors R1 and R2 is compared with the internal reference voltage by the error amplifier. The V_{OUT} pin is then driven by the subsequent output signal. The output voltage at the V_{OUT} pin is controlled and stabilized by a system of negative feedback.

V_{BIAS} pin is power supply pin for output voltage control circuit, protection circuit and CE circuit. Also, the V_{BIAS} pin supplies some current as output current. V_{IN} pin is connected to a driver transistor and provides output current.

In order to obtain high efficient output current through low on-resistance, please take enough $V_{GS} (=V_{BIAS} - V_{OUT(E)})$ of the driver transistor.

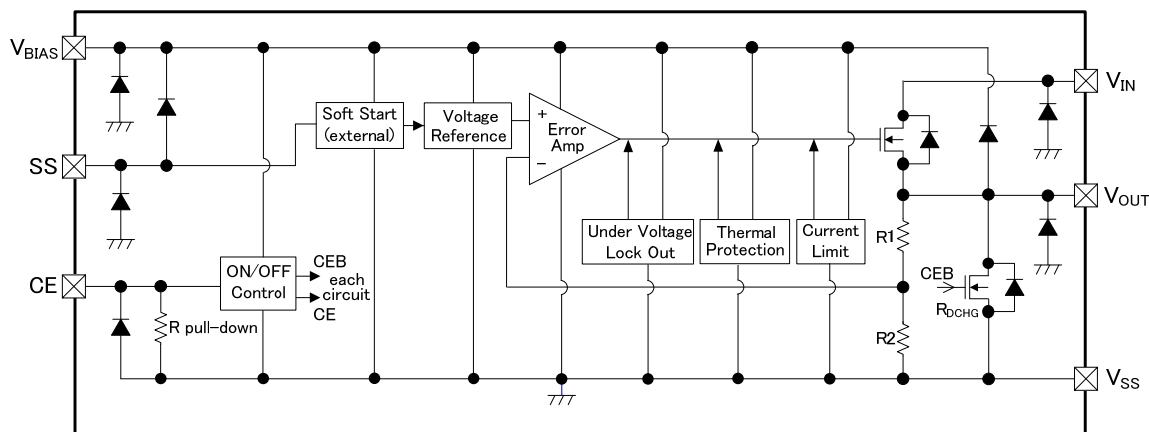


Figure1: XC6603 Series, Type A

<Soft-Start Function>

With the XC6603 (Type A), the inrush current (I_{RUSH}) from V_{IN} to V_{OUT} for charging C_L at start-up can be reduced and makes the V_{IN} stable.

With connecting a soft-start capacitor to the SS pin, rise time of the reference voltage (V_{ref}) is adjusted, then soft-start time can be set freely. The inrush current conflicts with the soft-start time, so that the inrush current is decreased if the soft-start time is set longer.

Please also note that the inrush current is depended on C_L or V_{BIAS} . When C_L or V_{BIAS} is larger, the inrush current becomes larger. Please set an appropriate soft-start time under the conditions of use.

When the SS pin is left open, soft-start circuit will not operate.

Soft-start time is calculated by the following formulas.

$$t_{SS} = C_{SS} \times V_{soft} / I_{soft}$$

t_{SS} : Soft-start time

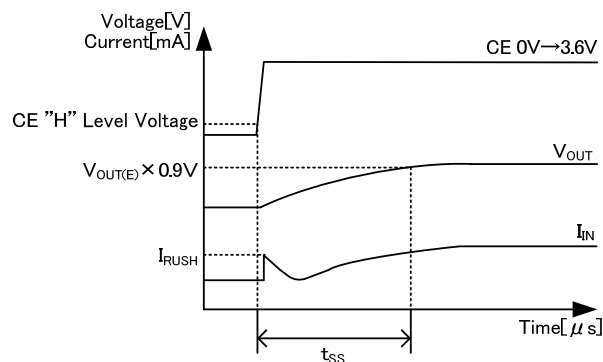
C_{SS} : Soft-start capacitance

V_{soft} : Soft-start threshold voltage

I_{soft} : SS pin current

Figure2: XC6603 Series, C_{SS} Range of use

SOFT-START CAPACITOR	SOFT-START TIME
C_{SS}	t_{SS} (TYP.)
$\sim 0.01 \mu F$	$\sim 2.17ms$



XC6603 Series, Soft-start

■ OPERATIONAL DESCRIPTION (Continued)

<Current Limiter, Short-Circuit Protection>

The XC6603 series includes a combination of a fixed current limiter circuit and a foldback short-circuit protection. When the output current reaches the current limit, the output voltage drops and this operation makes the output current foldback to be decreased.

<Thermal Shutdown Circuit (TSD) >

When the junction temperature of the built-in driver transistor reaches the temperature limit, the thermal shutdown circuit operates and the driver transistor will be set to OFF. The IC resumes its operation when the thermal shutdown function is released and the IC's operation is automatically restored because the junction temperature drops to the level of the thermal shutdown release temperature.

<Under Voltage Lock Out (UVLO) >

When the V_{BIAS} pin and V_{IN} pin voltage drops, the output driver transistor is set to OFF by UVLO function to prevent false output caused by unstable operation of the internal circuitry. When the V_{BIAS} pin voltage and the V_{IN} pin voltage rises at release voltage, the UVLO function is released. The driver transistor is turned ON and start to operate voltage regulation.

<CE Pin>

The XC6603 internal circuitry can be shutdown via the signal to the CE pin. In shutdown mode with CE low level voltage, the V_{OUT} pin will be pulled down to the V_{SS} level via C_L discharge resistance (R_{DCHG}) placed in parallel to R1 and R2.

The CE pin has pull-down circuitry so that CE input current flows during IC operation. If the CE pin voltage is taken from V_{BIAS} pin or V_{SS} pin then logic is fixed and the IC will operate normally. However, supply current may increase as a result of through current in the IC's internal circuitry when medium voltage is input.

< C_L High Speed Auto-Discharge>

XC6603 series can quickly discharge the electric charge at the output capacitor (C_L) via the internal transistor located between the V_{OUT} pin and the V_{SS} pin when a low signal to the CE pin which enables a whole IC circuit put into OFF state. When the IC is disabled, electric charge at the output capacitor (C_L) is quickly discharged so that it could avoids malfunction. Discharge time of the output capacitor (C_L) is set by the C_L auto-discharge resistance (R_{DCHG}) and the output capacitor (C_L). By setting time constant of a C_L auto-discharge resistance value (R_{DCHG}) and an output capacitor value (C_L) as ($\tau = C_L \times R_{DCHG}$), the output voltage after discharge via the internal transistor is calculated by the following formula. Please also note R_{DCHG} is depended on V_{BIAS} . When V_{BIAS} is larger, R_{DCHG} is smaller.

$$V = V_{OUT(E)} \times e^{-t/\tau} \quad \text{or} \quad t = \tau \ln (V_{OUT(E)} / V)$$

V: Output voltage during discharge

$V_{OUT(E)}$: Initial Output voltage

t: Discharge time

τ : $C_L \times R_{DCHG}$

<Low ESR Capacitor>

With the XC6603 series, a stable output voltage is achievable even if used with low ESR capacitors, as a phase compensation circuit is built-in. The output capacitor (C_L) should be connected as close to V_{OUT} pin and V_{SS} pin to obtain stable phase compensation. Values required for the phase compensation are as the table below.

For a stable power input, please connect a bias capacitor (C_{BIAS}) between the V_{BIAS} pin and the V_{SS} pin. Also, please connect an input capacitor (C_{IN}) between the V_{IN} pin and the V_{SS} pin. In order to ensure the stable phase compensation while avoiding run-out of values, please use the capacitor (C_{BIAS} , C_{IN} and C_L) which does not depend on bias or temperature too much. The table below (Figure 3) shows recommended values of C_{BIAS} , C_{IN} and C_L .

Figure 3: Recommended Values of C_{BIAS} , C_{IN} and C_L (MIN.)

OUTPUT VOLTAGE RANGE	BIAS CAPACITOR	INPUT CAPACITOR	OUTPUT CAPACITOR
$V_{OUT(T)}$	C_{BIAS}	C_{IN}	C_L
0.5V~1.8V	1.0 μ F	1.0 μ F	2.2 μ F

■NOTES ON USE

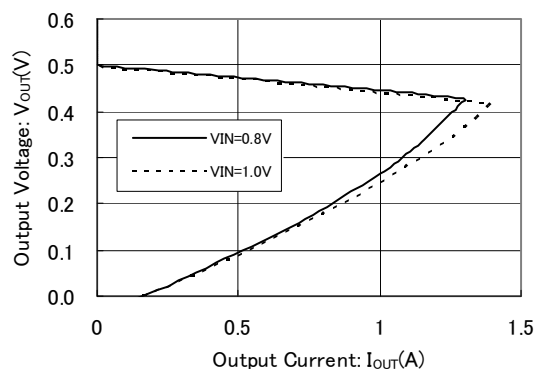
1. For temporary, transitional voltage drop or voltage rising phenomenon, the IC is liable to malfunction should the ratings be exceeded.
2. Where wiring impedance is high, operations may become unstable due to noise and/or phase lag depending on output current. Please keep the resistance low for the V_{BIAS} , V_{IN} and V_{SS} wiring in particular.
3. Please wire the C_{BIAS} , C_{IN} and C_L as close to the IC as possible.
4. Capacitances of these capacitors (C_{BIAS} , C_{IN} , C_L) are decreased by the influences of bias voltage and ambient temperature. Care shall be taken for capacitor selection to ensure stability of phase compensation from the point of ESR influence.
5. When it is used in a quite small input / output dropout voltage, output may go into unstable operation. Please test it thoroughly before using it in production.
6. Torex places an importance on improving our products and their reliability.
We request that users incorporate fail-safe designs and post-aging protection treatment when using Torex products in their systems.

TYPICAL PERFORMANCE CHARACTERISTICS

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

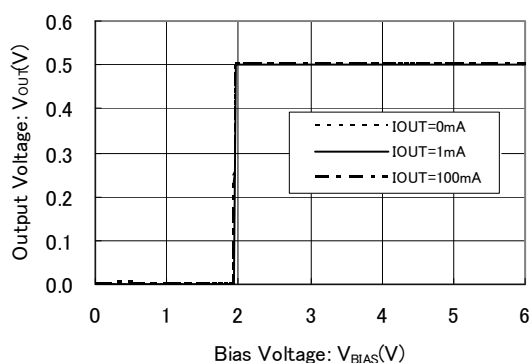
(1) Output Voltage vs. Output Current

XC6603A051MR-G

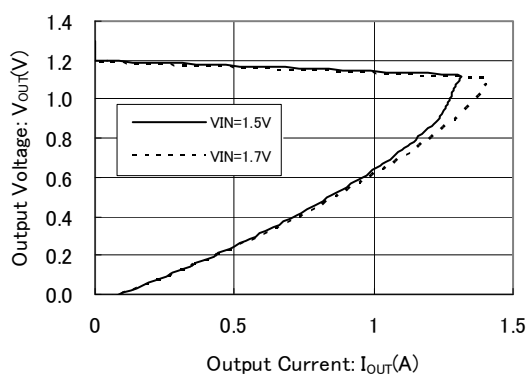


(2) Output Voltage vs. Bias Voltage

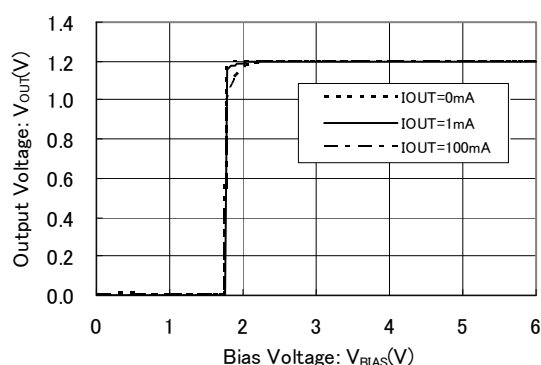
XC6603A051xR-G



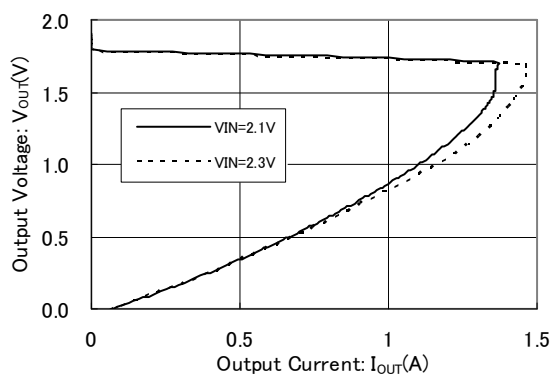
XC6603A121MR-G



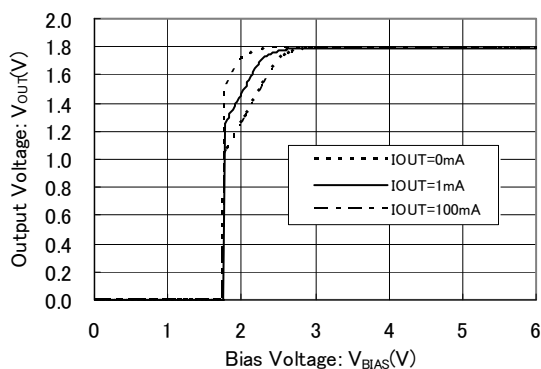
XC6603A121xR-G



XC6603A181MR-G



XC6603A181xR-G



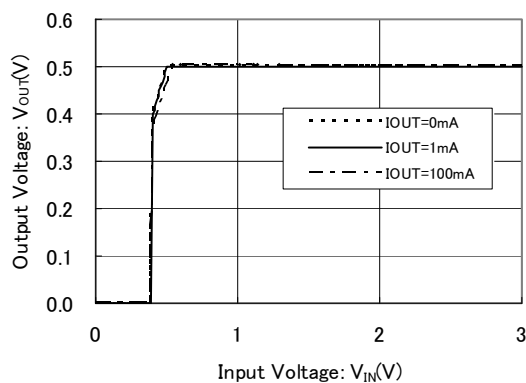
* Mount conditions affect heat dissipation. Thermal shutdown may start to operate before reaching the current limit.

■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

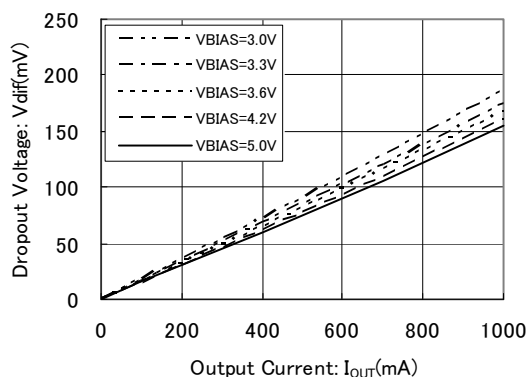
(3) Output Voltage vs. Input Voltage

XC6603A051xR-G

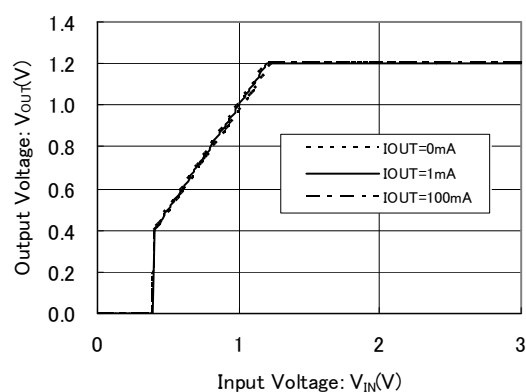


(4) Dropout Voltage vs. Output Current

XC6603A121MR-G

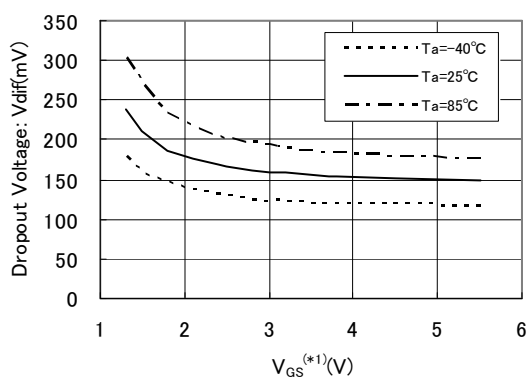


XC6603A121xR-G

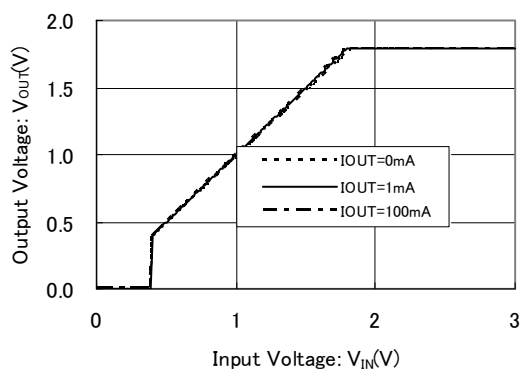


XC6603Axx1MR-G

$I_{OUT}=1A$



XC6603A181xR-G

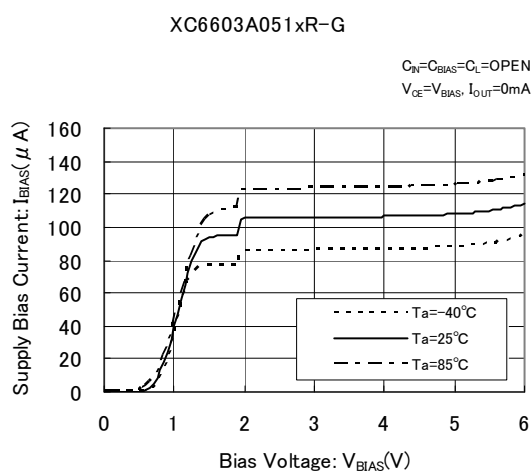


(*1) V_{GS} is a Gate-Source voltage of the driver transistor that is defined as the value of $V_{BIAS} - V_{OUT(E)}$.
A value of the dropout voltage is determined by the value of the V_{GS} .

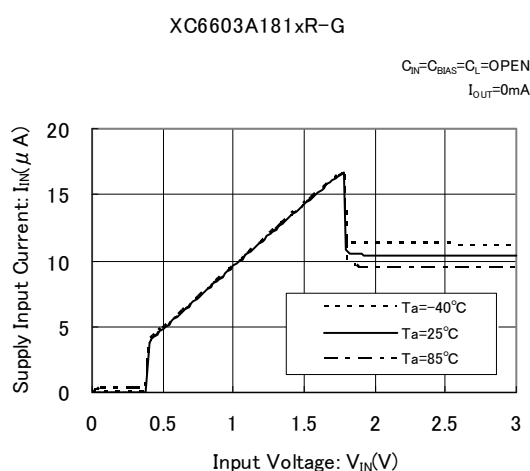
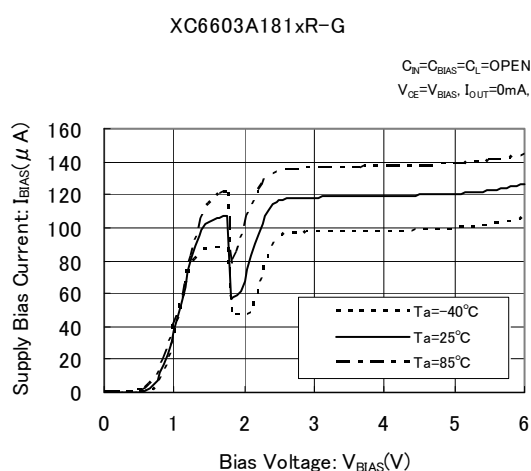
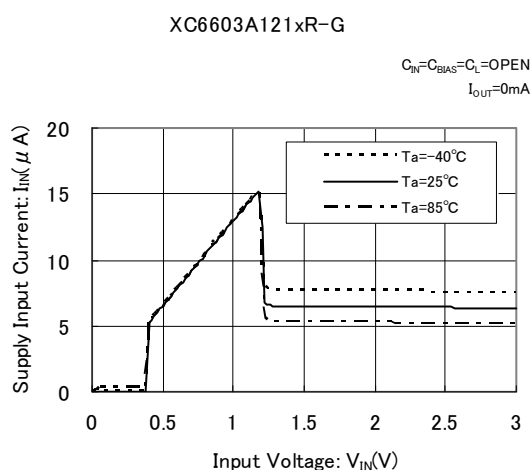
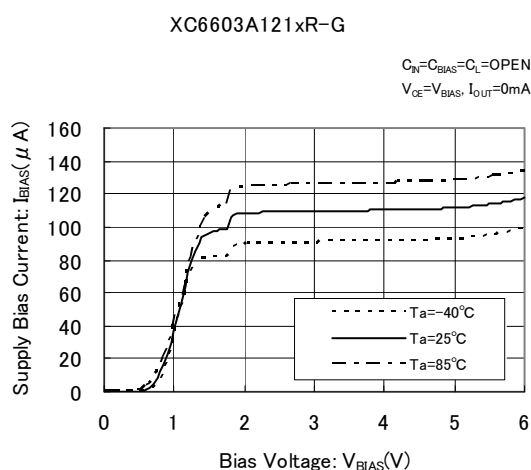
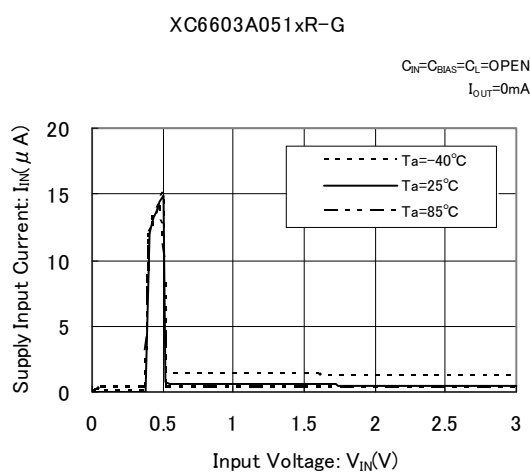
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

(5) Supply Bias Current vs. Bias Voltage



(6) Supply Input Current vs. Input Voltage

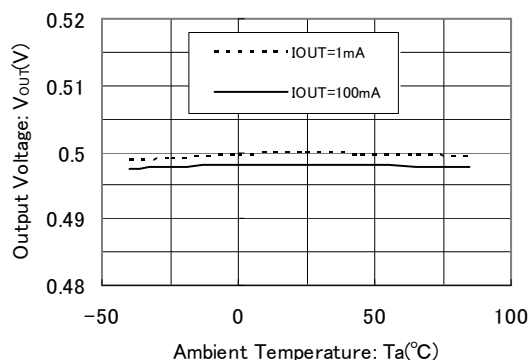


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

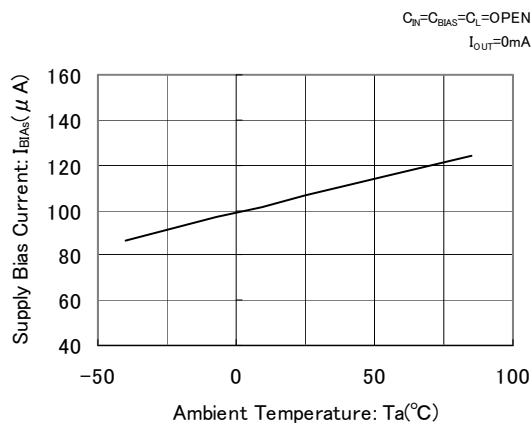
(7) Output Voltage vs. Ambient Temperature

XC6603A051xR-G

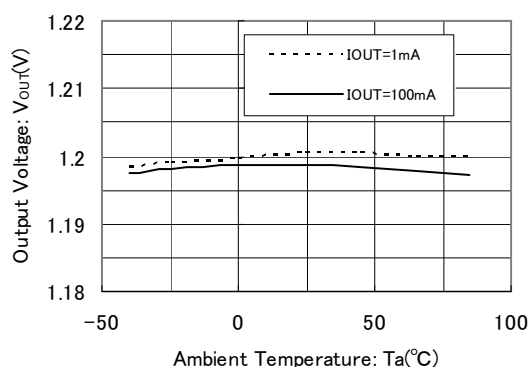


(8) Supply Bias Current vs. Ambient Temperature

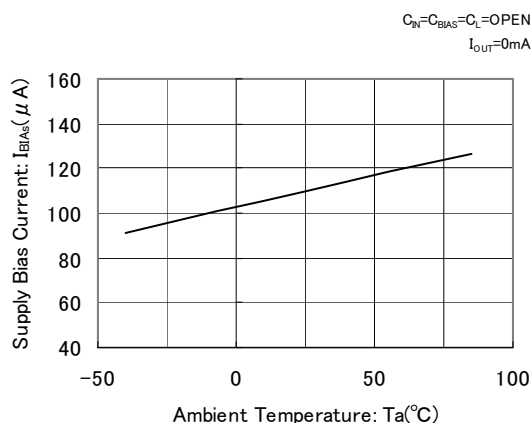
XC6603A051xR-G



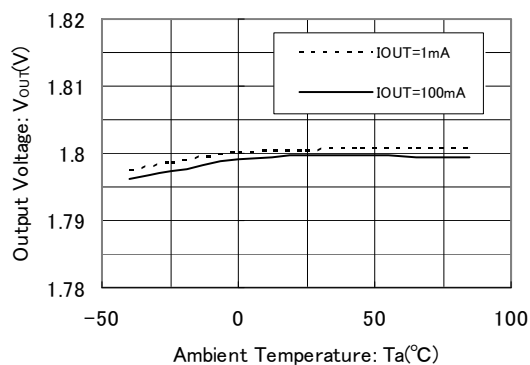
XC6603A121xR-G



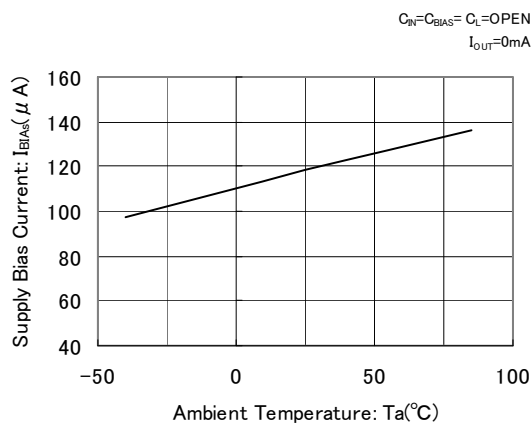
XC6603A121xR-G



XC6603A181xR-G



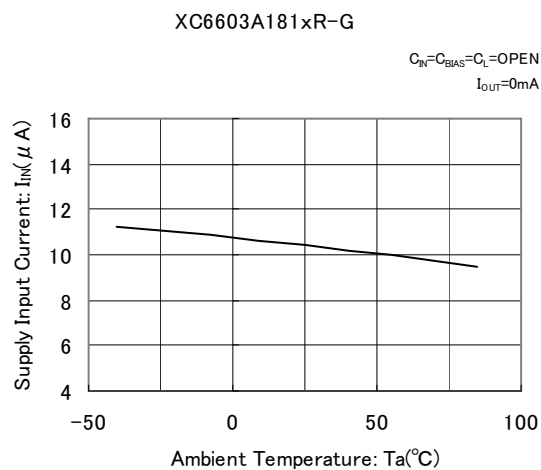
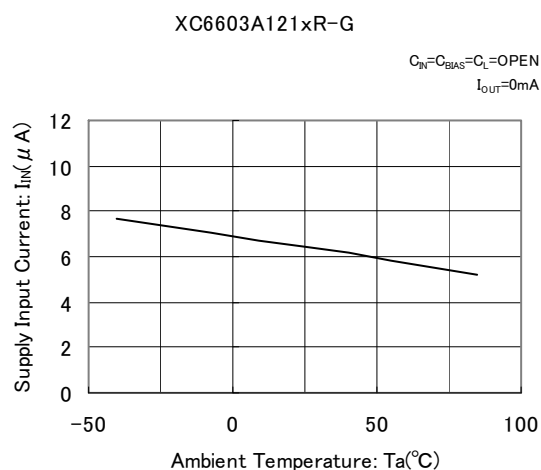
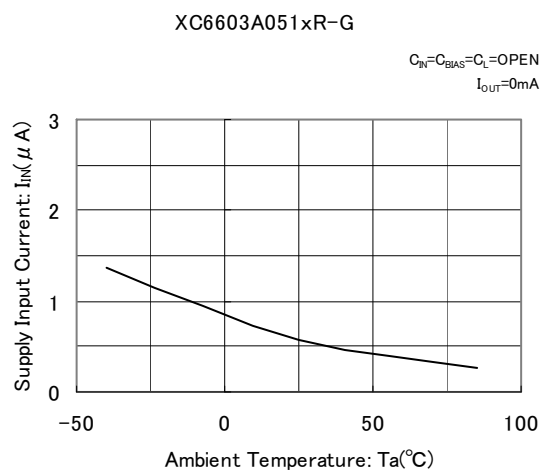
XC6603A181xR-G



TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

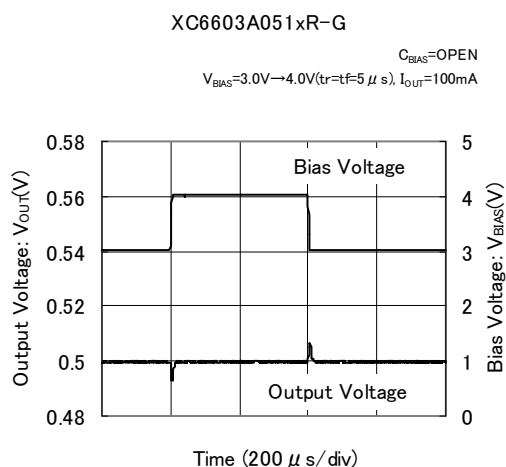
(9) Supply Input Current vs. Ambient Temperature



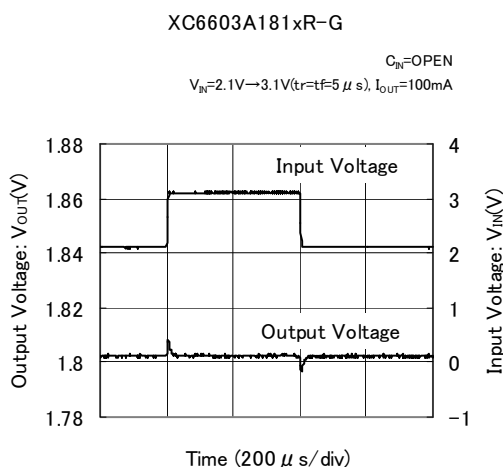
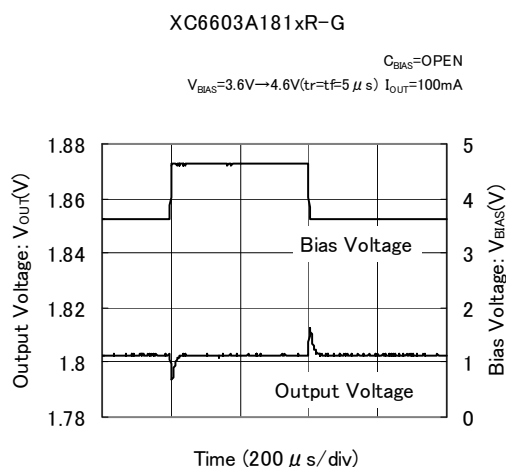
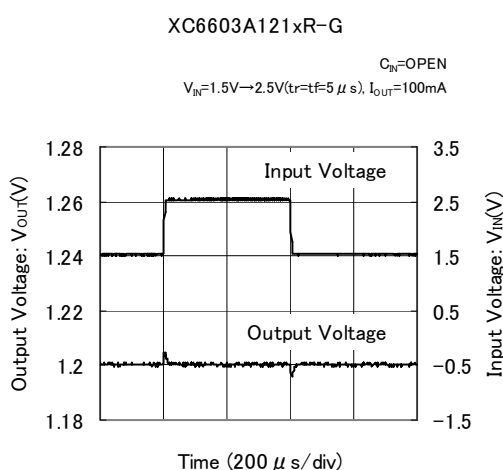
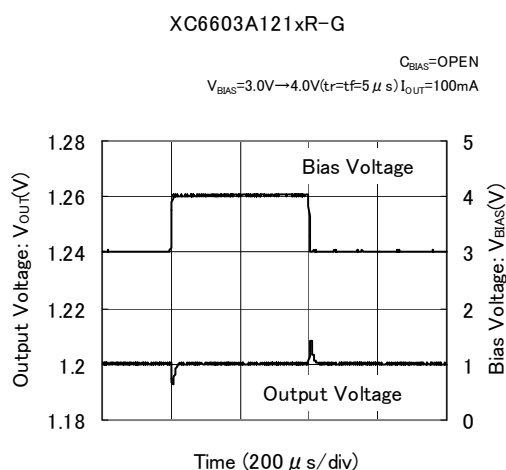
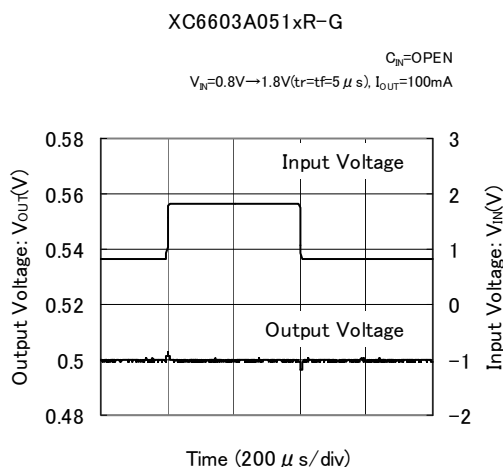
■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

(10) Bias Transient Response



(11) Input Transient Response



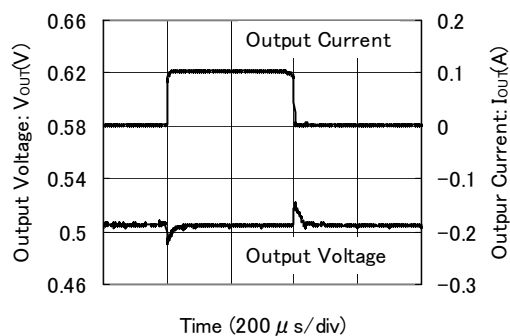
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

(12) Load Transient Response

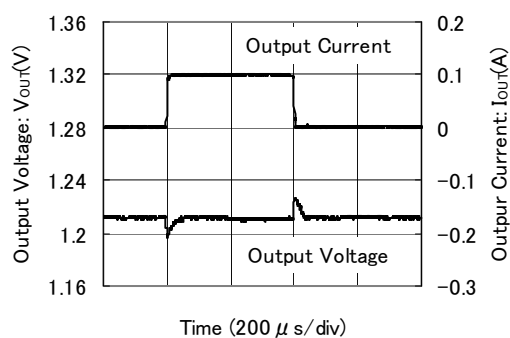
XC6603A051xR-G

$I_{OUT}=1mA \leftrightarrow 100mA (tr=tf=5\mu s)$



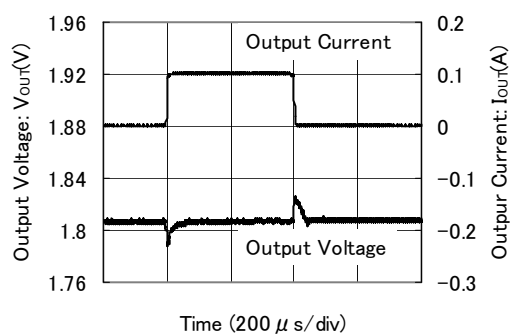
XC6603A121xR-G

$I_{OUT}=1mA \leftrightarrow 100mA (tr=tf=5\mu s)$



XC6603A181xR-G

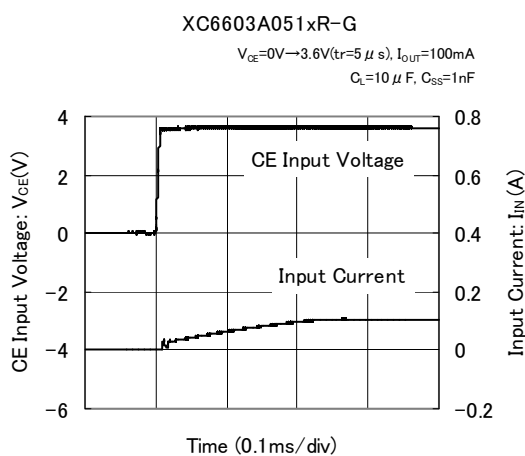
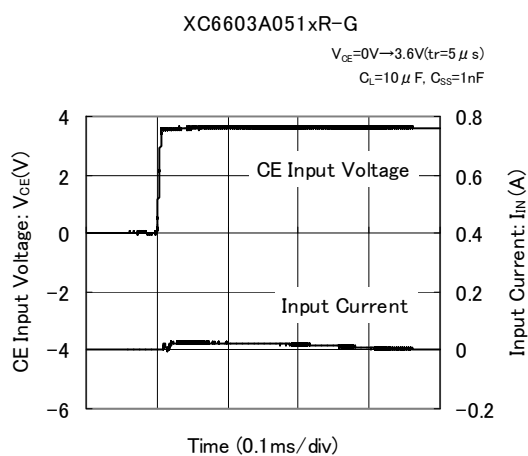
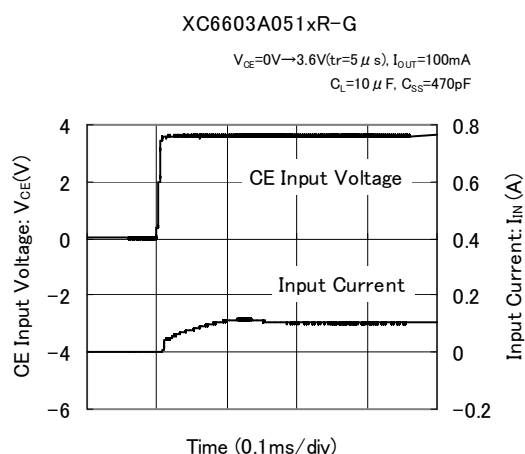
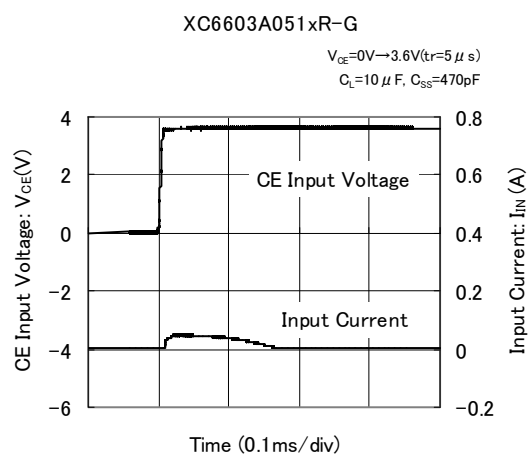
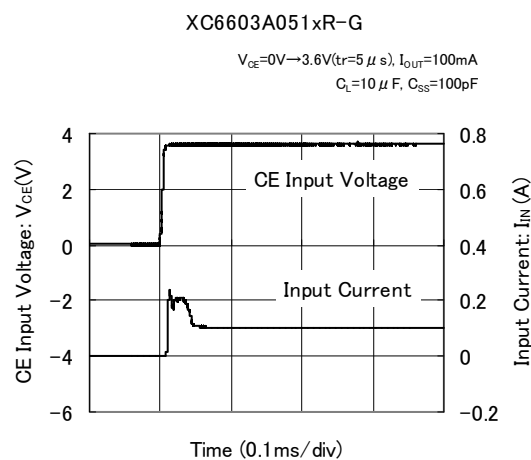
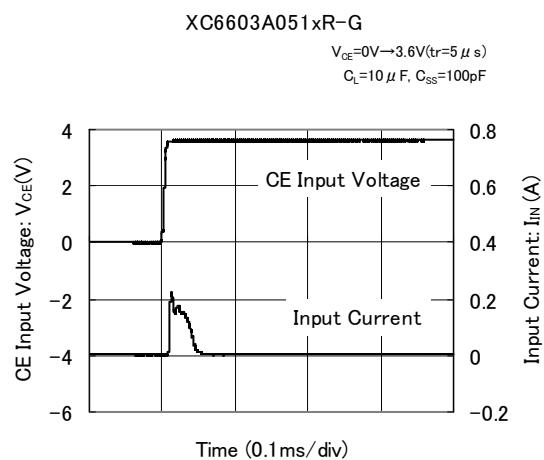
$I_{OUT}=1mA \leftrightarrow 100mA (tr=tf=5\mu s)$



■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

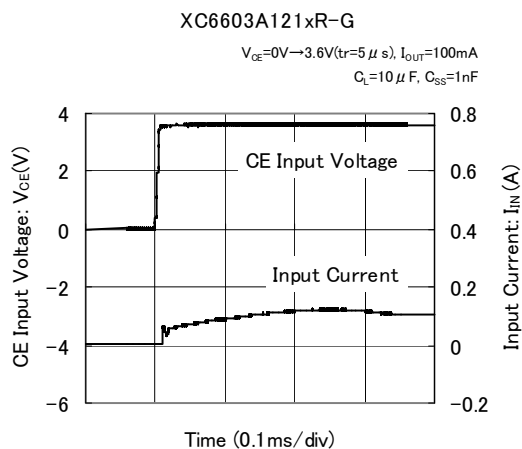
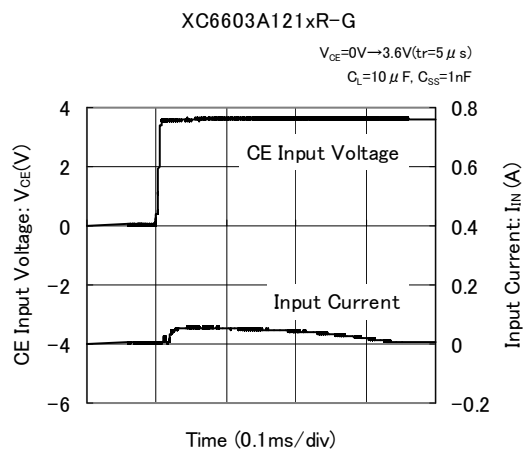
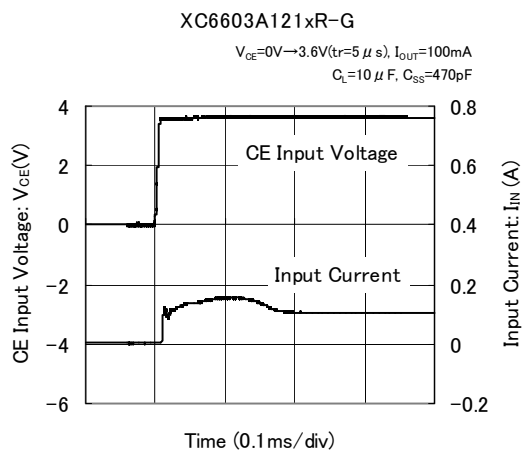
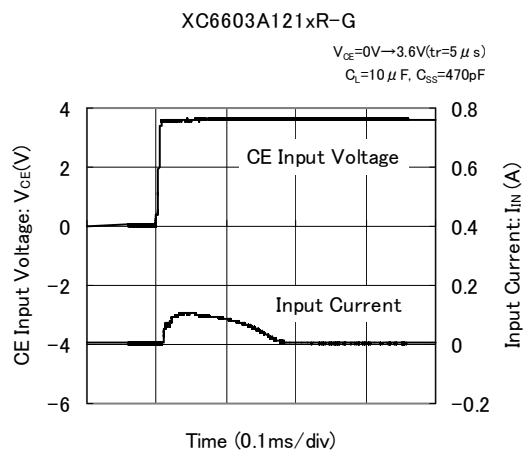
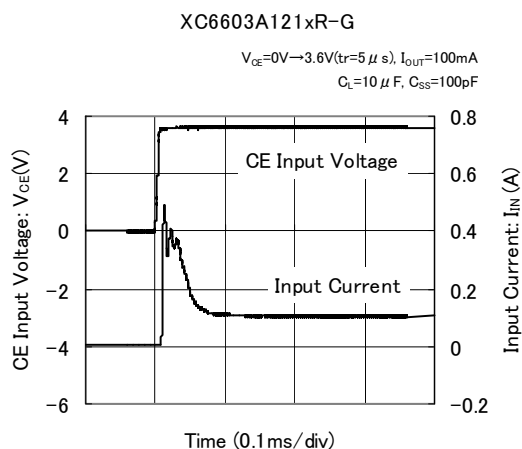
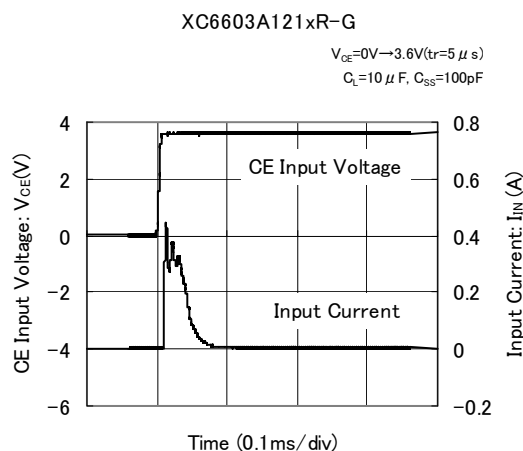
(13) CE Input Response



TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

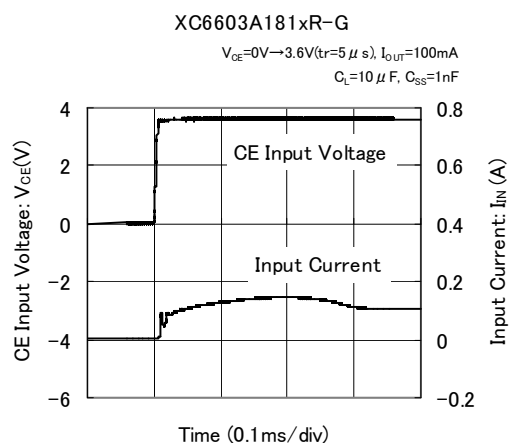
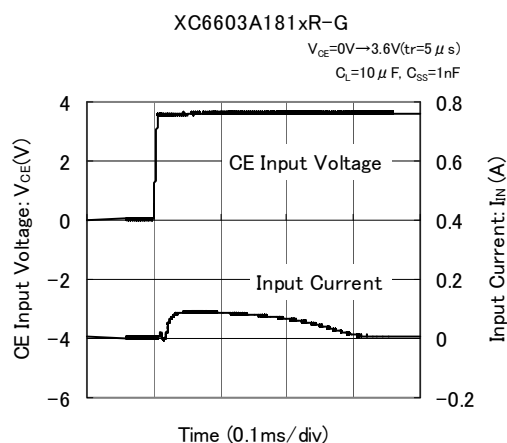
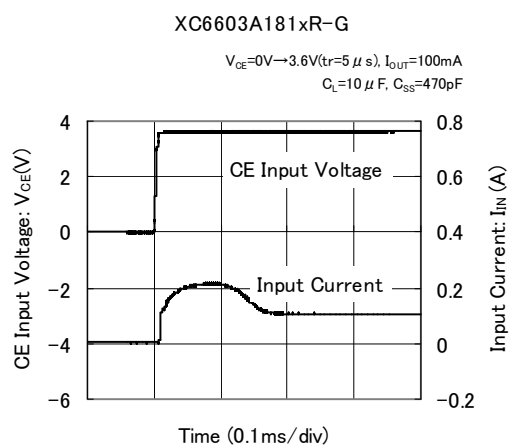
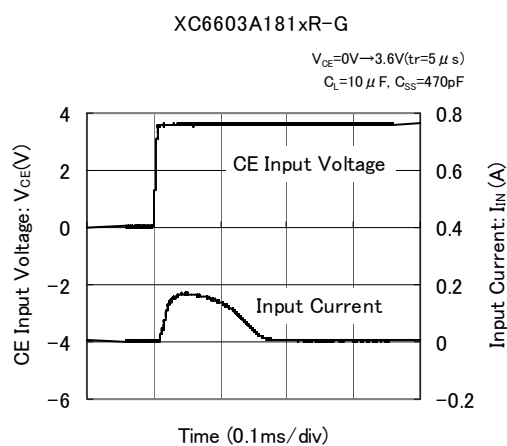
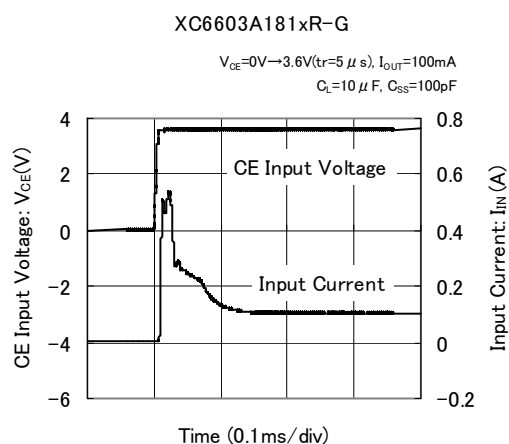
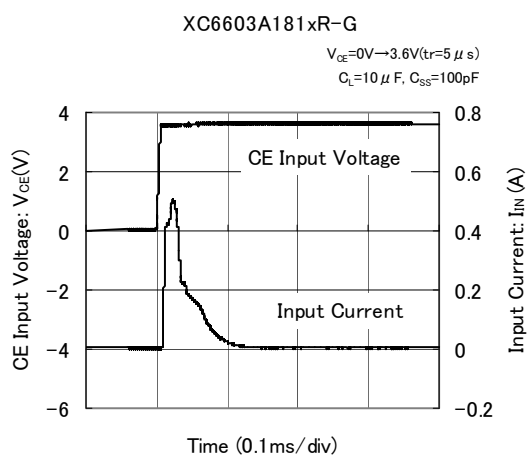
(13) CE Input Response (Continued)



■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

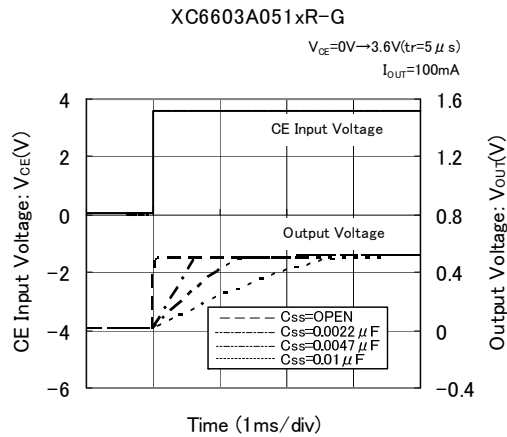
(13) CE Input Response (Continued)



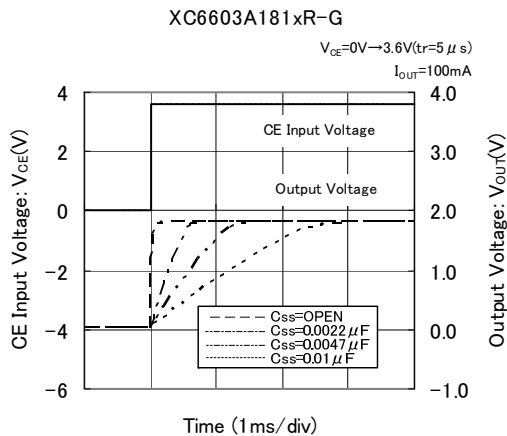
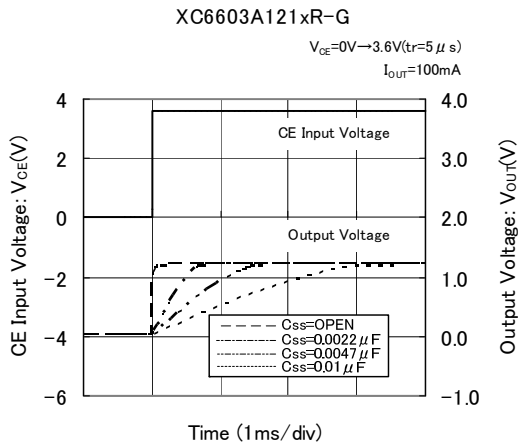
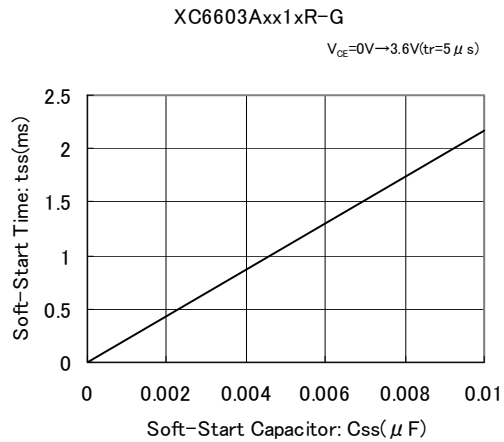
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

(14) CE Rising Response Time



(15) Adjustable Soft-start Time

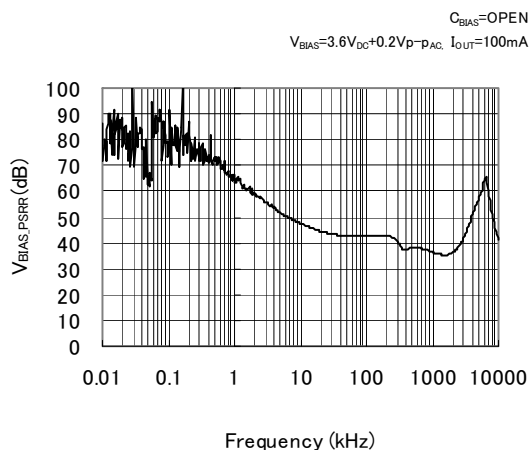


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

* Unless otherwise stated, $V_{BIAS}=V_{CE}=3.6V$, $V_{IN}=V_{OUT(T)}+0.3V$, $I_{OUT}=1mA$, SS Pin=OPEN, $C_{BIAS}=C_{IN}=1.0\mu F$, $C_L=2.2\mu F$, $T_a=25$

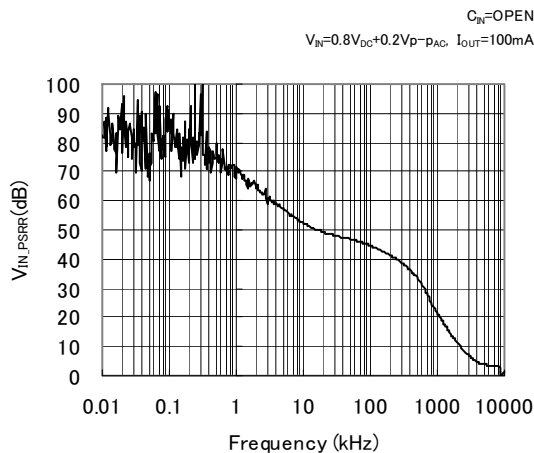
(16) Bias Voltage Ripple Rejection Rate

XC6603A051xR-G

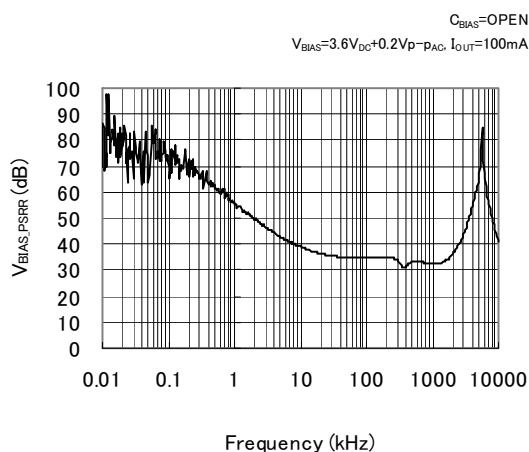


(17) Input Voltage Ripple Rejection Rate

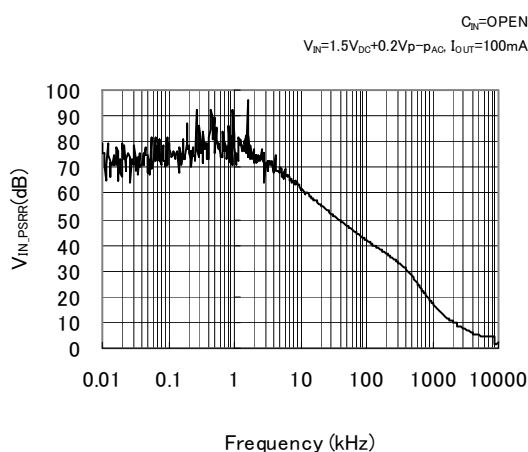
XC6603A051xR-G



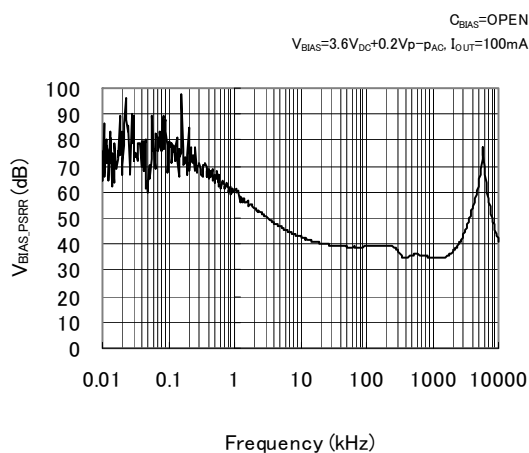
XC6603A121xR-G



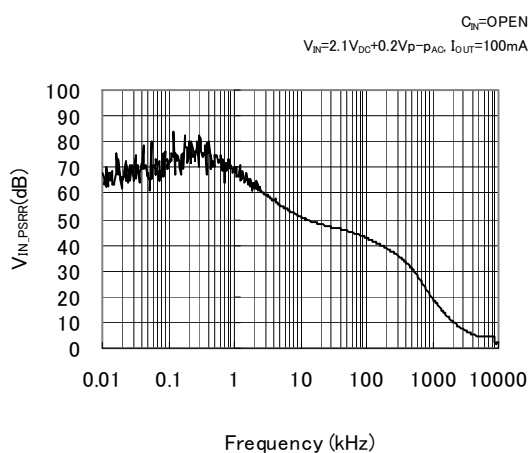
XC6603A121xR-G



XC6603A181xR-G



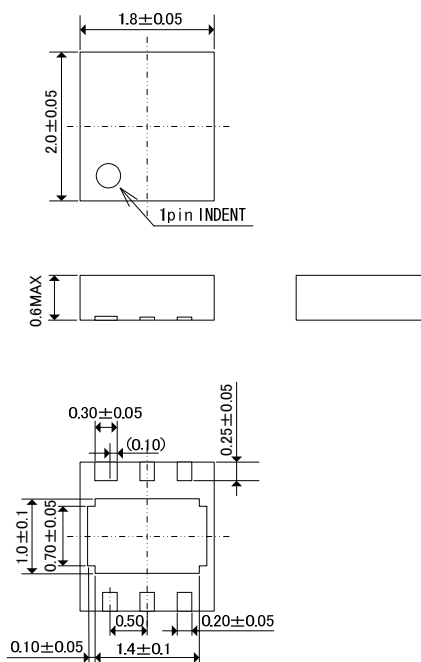
XC6603A181xR-G



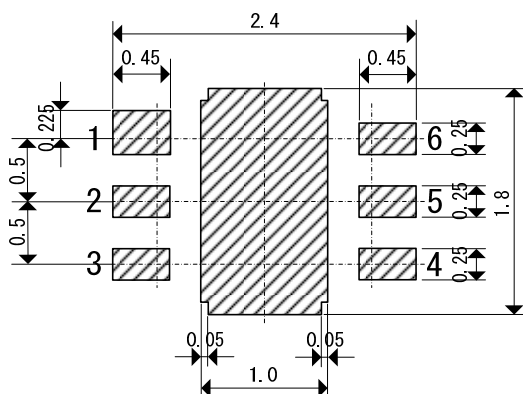
PACKAGING INFORMATION

USP-6C

(unit : mm)

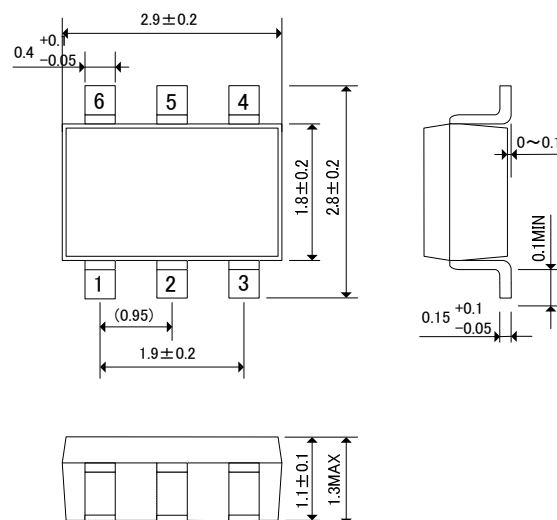


USP-6C Reference Pattern Layout (unit: mm)

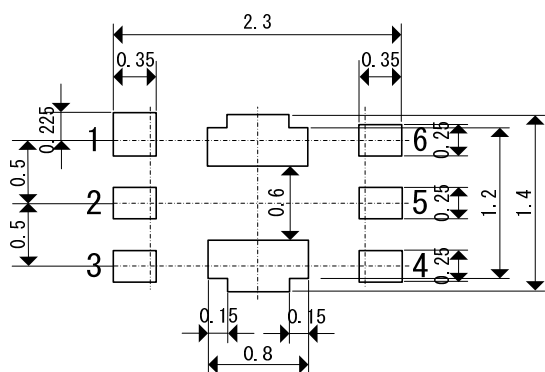


SOT-26W

(unit : mm)



USP-6C Reference Metal Mask Design (unit: mm)



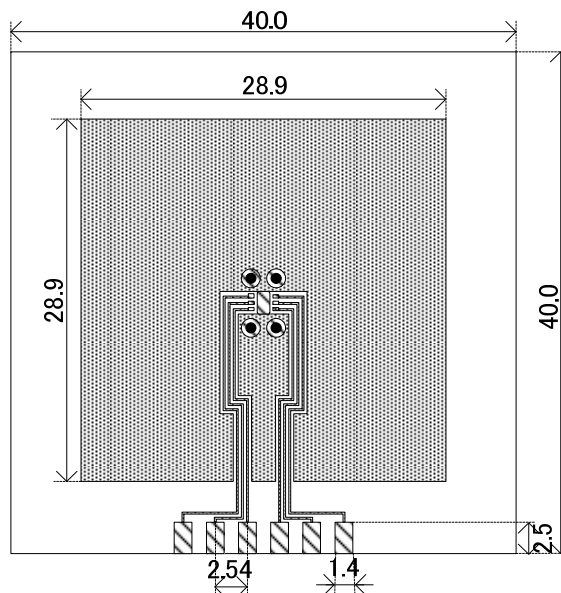
PACKAGING INFORMATION (Continued)

USP-6C Power Dissipation

Power dissipation data for the USP-6C is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board
Ambient: Natural convection
Soldering: Lead (Pb) free
Board: Dimensions 40 x 40 mm (1600 mm² in one side)
Copper (Cu) traces occupy 50% of the board area
In top and back faces
Package heat-sink is tied to the copper traces
Material: Glass Epoxy (FR-4)
Thickness: 1.6 mm
Through-hole: 4 x 0.8 Diameter

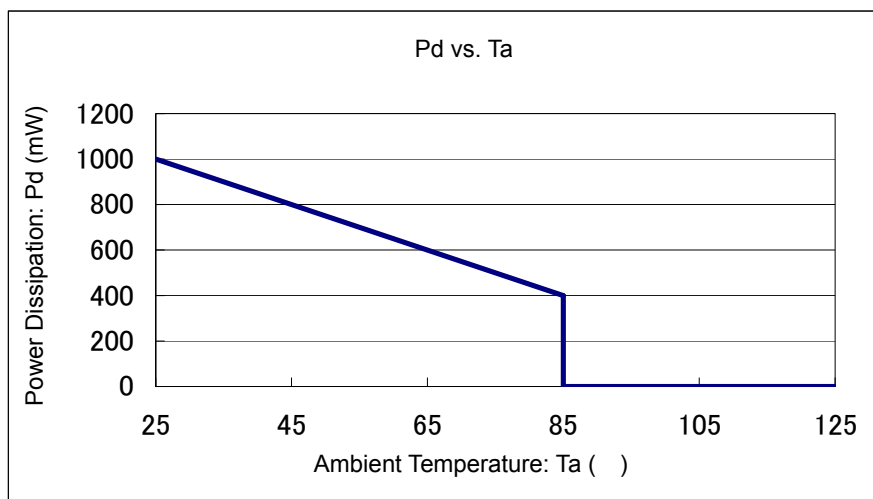


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount ($T_j \text{ max} = 125$)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1000	100.00
85	400	



PACKAGING INFORMATION (Continued)

SOT-26W Power Dissipation

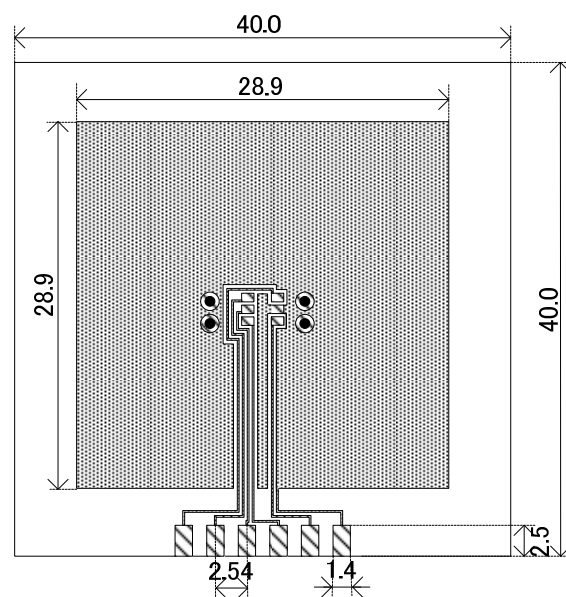
Power dissipation data for the SOT-26W is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition:	Mount on a board
Ambient:	Natural convection
Soldering:	Lead (Pb) free
Board:	Dimensions 40 x 40 mm (1600 mm ² in one side) Copper (Cu) traces occupy 50% of the board area In top and back faces Package heat-sink is tied to the copper traces (Board of SOT-26 is used.)
Material:	Glass Epoxy (FR-4)
Thickness:	1.6 mm
Through-hole:	4 x 0.8 Diameter

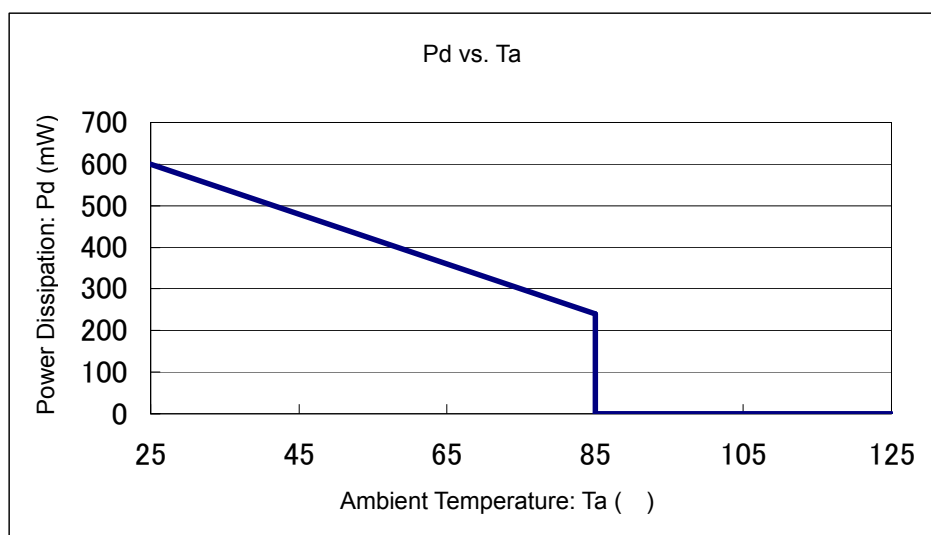


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount ($T_j \text{ max} = 125$)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	600	166.67
85	240	



MARKING RULE

represents product series

MARK	PRODUCT SERIES
S	XC6603A*****-G

represents output voltage

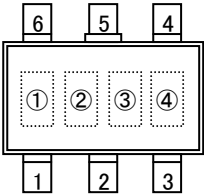
MARK	OUTPUT VOLTAGE (V)	MARK	OUTPUT VOLTAGE (V)
A	0.5	K	1.2
B	0.6	L	1.3
C	0.7	M	1.4
D	0.8	N	1.5
E	0.9	P	1.6
F	1.0	R	1.7
H	1.1	S	1.8

represents production lot number

01 to 09, 0A to 0Z, 11 to 9Z, A1 to A9, AA to Z9, B1 to ZZ in order.
(G, I, J, O, Q, W excluded)

*No character inversion used.

SOT-26W



MARKING RULE (Continued)

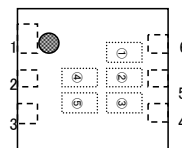
represents product series

MARK	PRODUCT SERIES
S	XC6603*****-G

represents regulator type

MARK	PRODUCT SERIES
A	XC6603A*****-G

USP-6C



represents output voltage

MARK	OUTPUT VOLTAGE (V)	MARK	OUTPUT VOLTAGE (V)
A	0.5	K	1.2
B	0.6	L	1.3
C	0.7	M	1.4
D	0.8	N	1.5
E	0.9	P	1.6
F	1.0	R	1.7
H	1.1	S	1.8

represents production lot number

01 to 09, 0A to 0Z, 11 to 9Z, A1 to A9, AA to Z9, B1 to ZZ in order.
(G, I, J, O, Q, W excluded)

*No character inversion used.

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(e.g. Atomic energy; aerospace; transport; combustion and associated safety equipment thereof.)
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